



鈦昇科技股份有限公司(8027) E&R ENGINEERING CORPORATION Operation Overview And Outlook

E&R
Jun 2024



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本簡報中如有對未來之展望，係反映本公司截至目前為止對於未來之看法，如未來有因任何事件或環境變遷，本公司並不負有更新資料之責任。

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議程 Agenda



公司簡介

Brief Introduction



公司產品

Products



公司展望

Future outlook



問答時間

Q&A



Brief Introduction 公司簡介

關於我們 About US



Kaohsiung
Headquarter



1994.10

Establish

2015.6

IPO (8027)

NT\$ 10.27E

Capital (2024/6)

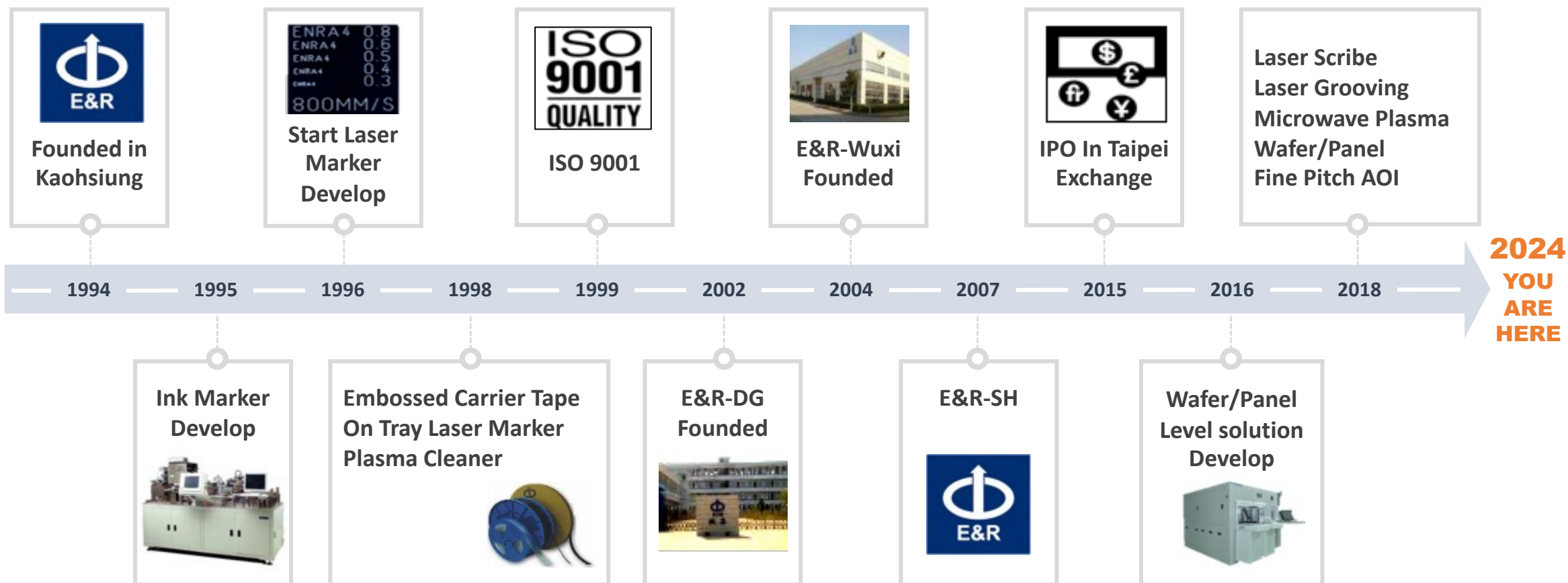
340+

Employee

10

Worldwide center

發展沿革 E&R Milestone





核心技術 E&R Core Technology

RF and Microwave



Plasma

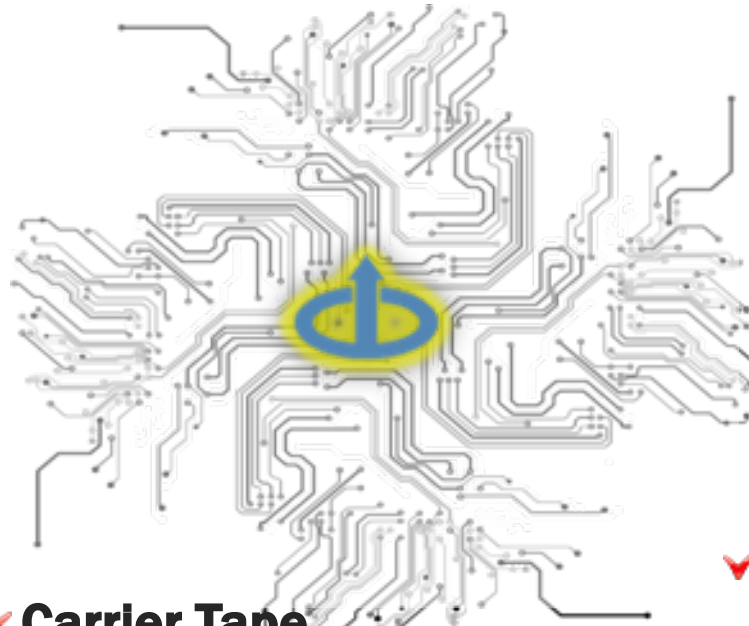
Plasma Clean RF / Microwave
Plasma Etching & Desmear
Wafer Plasma De-flash
Wafer Plasma Dicing



AI+AOI



AOI for surface
Inspection for inner stress



Carrier Tape



Laser Solution

*Nano, Pico, Femto
IR, SHG, UV*

Laser Marking
Laser Cutting
Laser Drilling
Laser Scribing
Laser Grooving
Laser Ablation
Laser De-bond
Laser Trench

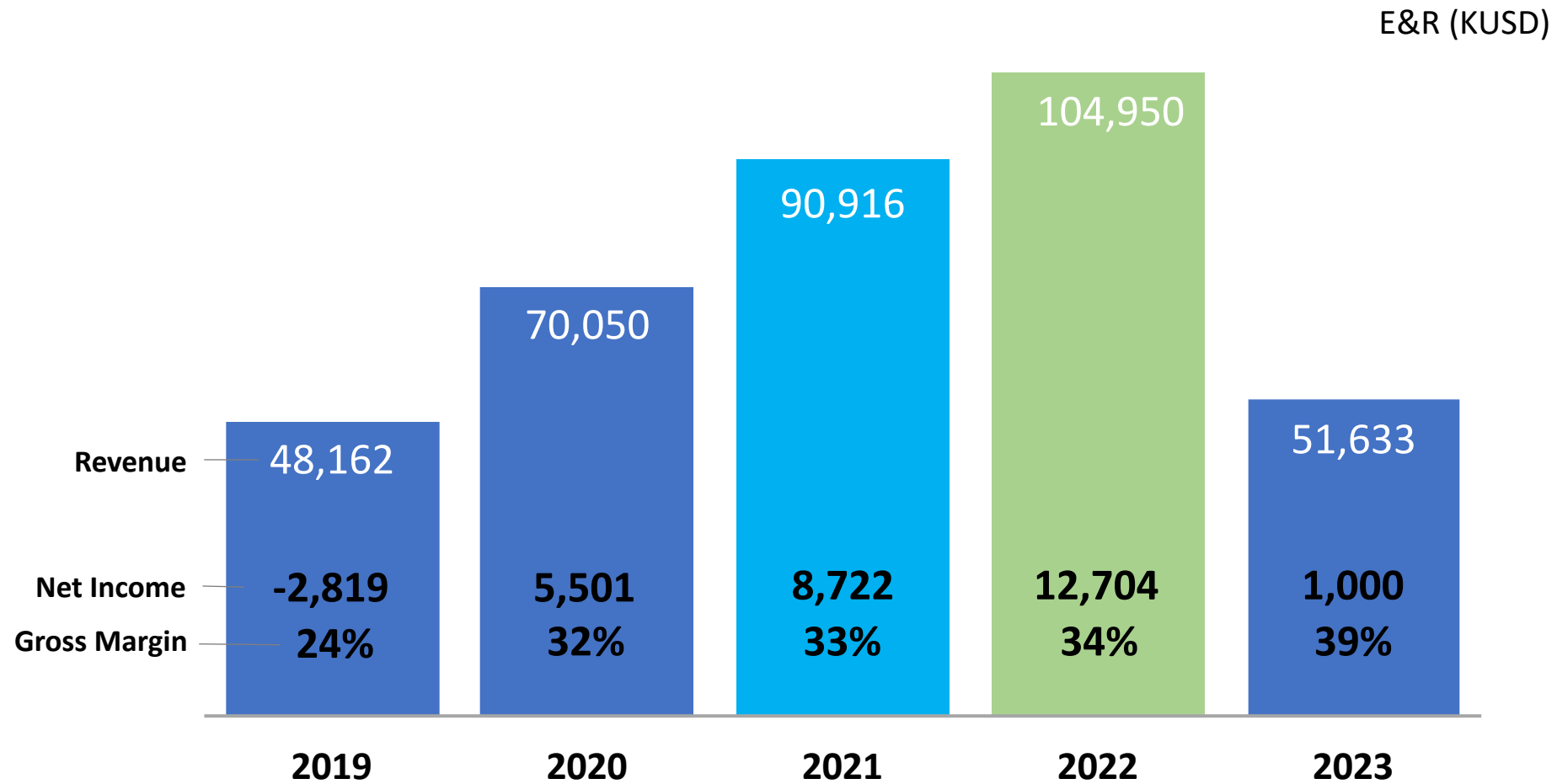


Automation

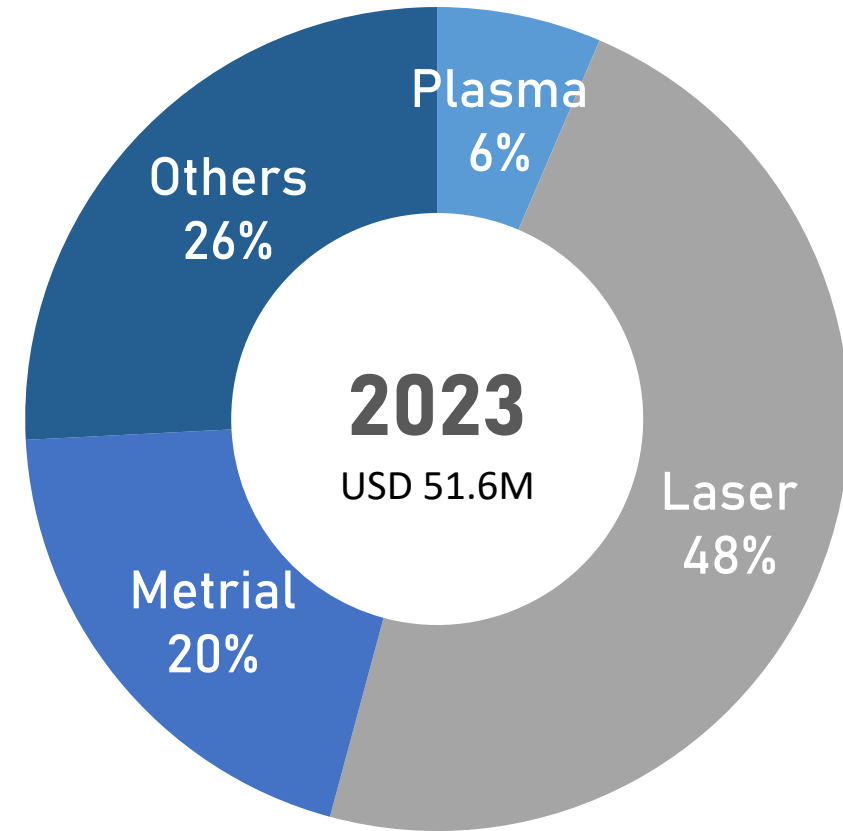
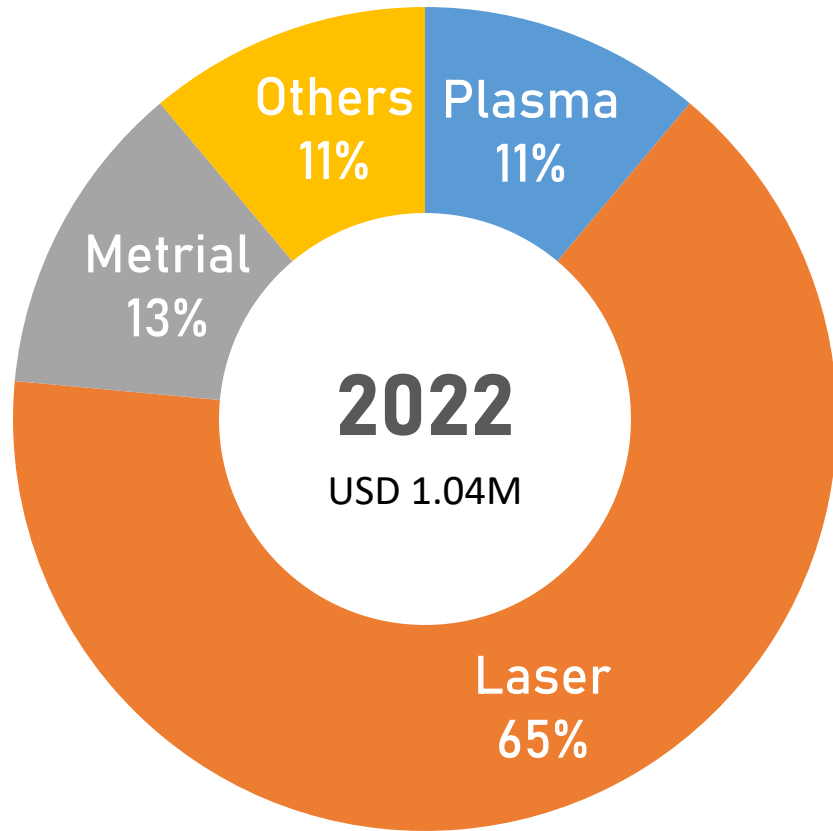
S2/S8, Gem-300, SECS/GEM

Semiconductor
uLED Industry
FPC/Substrate Industry

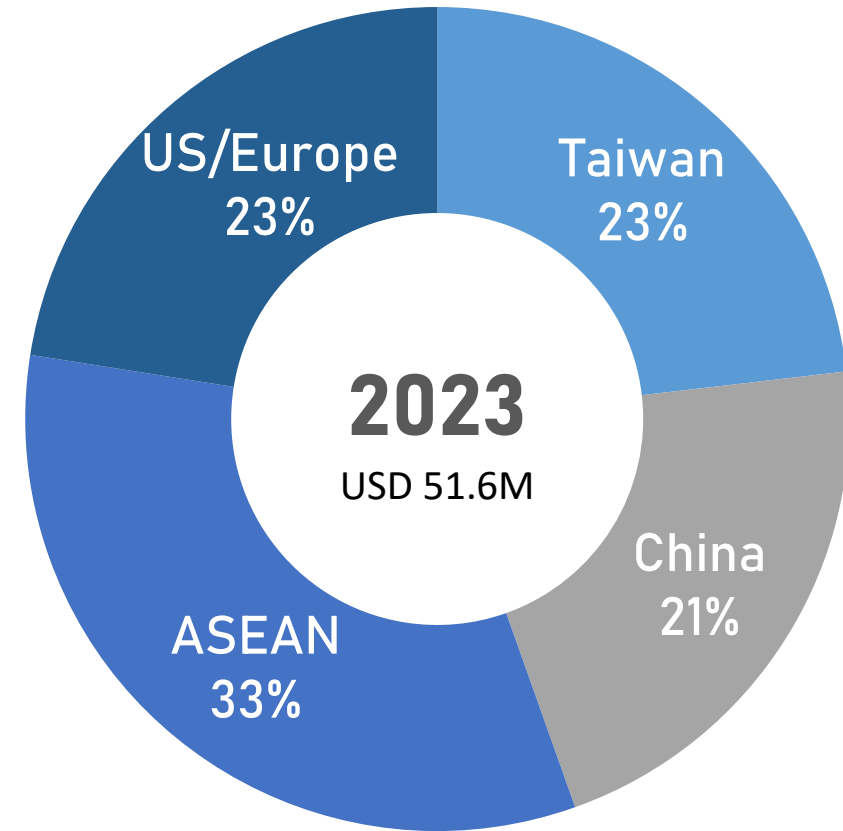
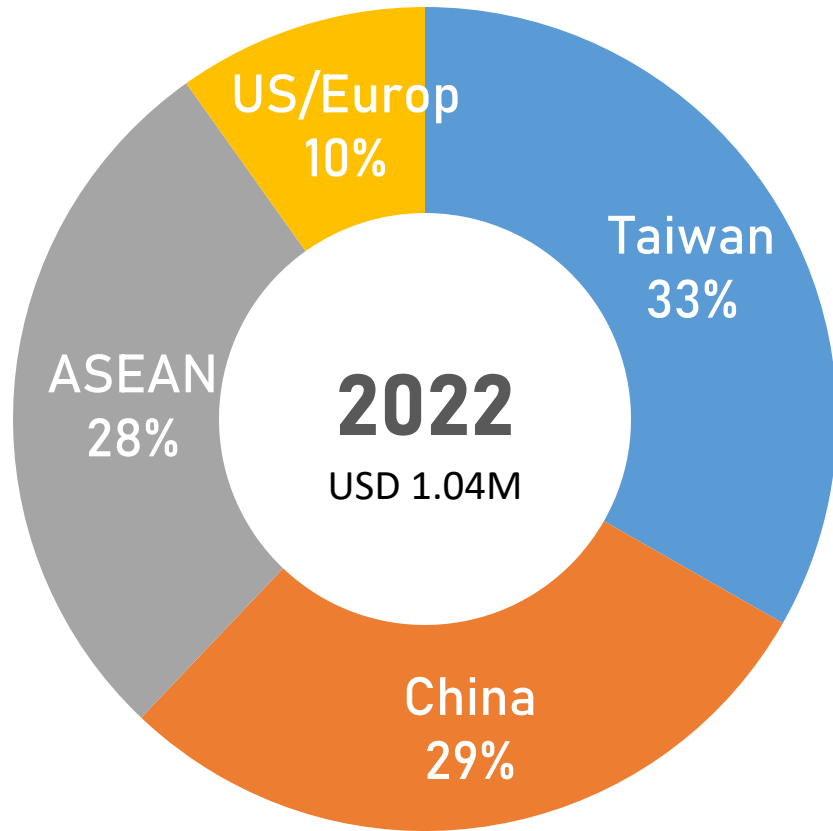
Finance status 2019-2023



Sales distribution by Product – 2022/2023



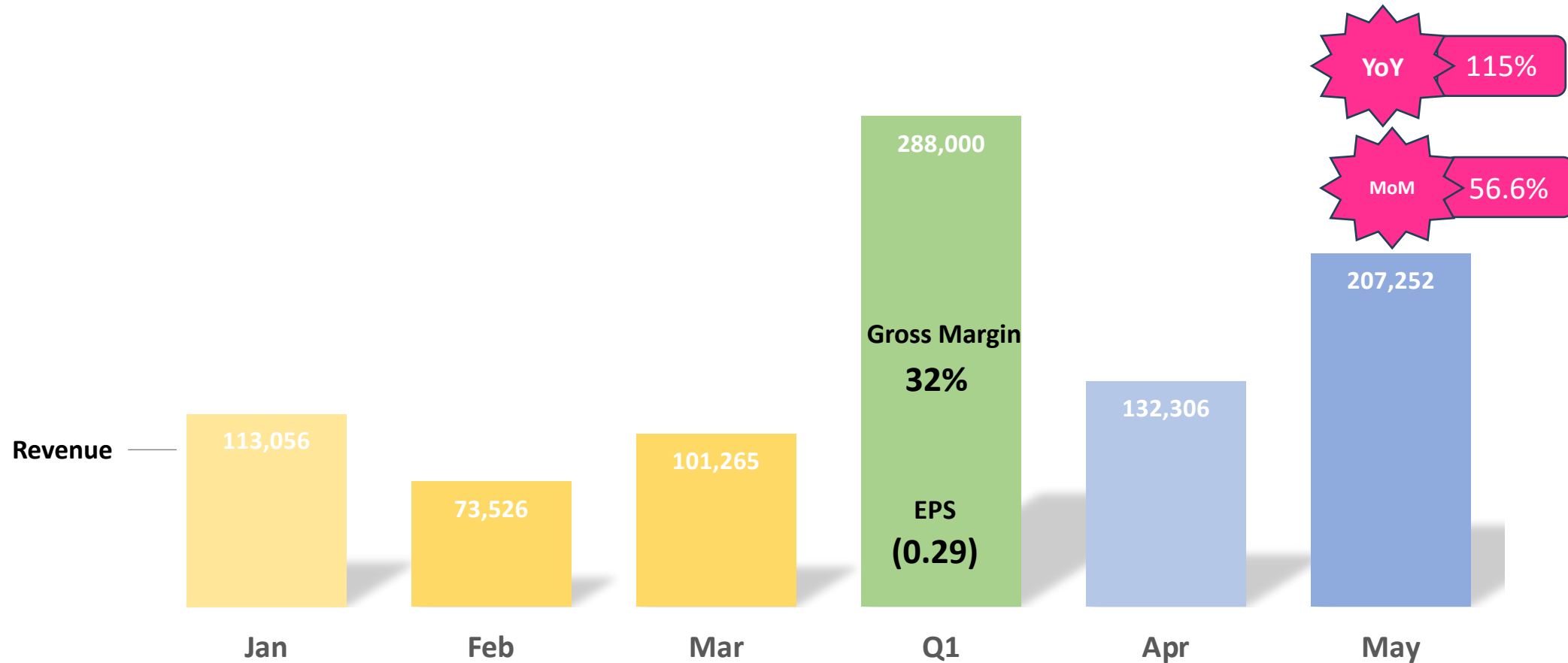
Sales distribution by Region – 2022/2023



Finance status 2024~



E&R (NTD)





客製化能力 Customization

提供客戶硬體和軟體上的客製化需求，在各式製程上提供多樣的應用解決方案。



研發技術經驗 R&D Technology

擁有二十年以上的中、後段封測研發經驗，並提供整體解決方案與新產品開發的服務。



全球據點即時服務 Global Service

全球技術服務支援，跨越距離，在第一時間提供服務。



品質優先 Quality First

提供卓越的產品，在地化生產，充分滿足客戶需求。



Products 公司產品



雷射設備

半導體雷射打印、雷射鑽孔、SIP切割晶圓切割、晶圓劃線、晶圓開槽等。



電漿設備

電子微接點有機物清除、氧化物清除、氧化矽沉積以及電漿切割等。



檢測設備

晶圓表面缺陷檢查、晶圓材料缺陷檢查、Micro LED表面缺陷檢查等。

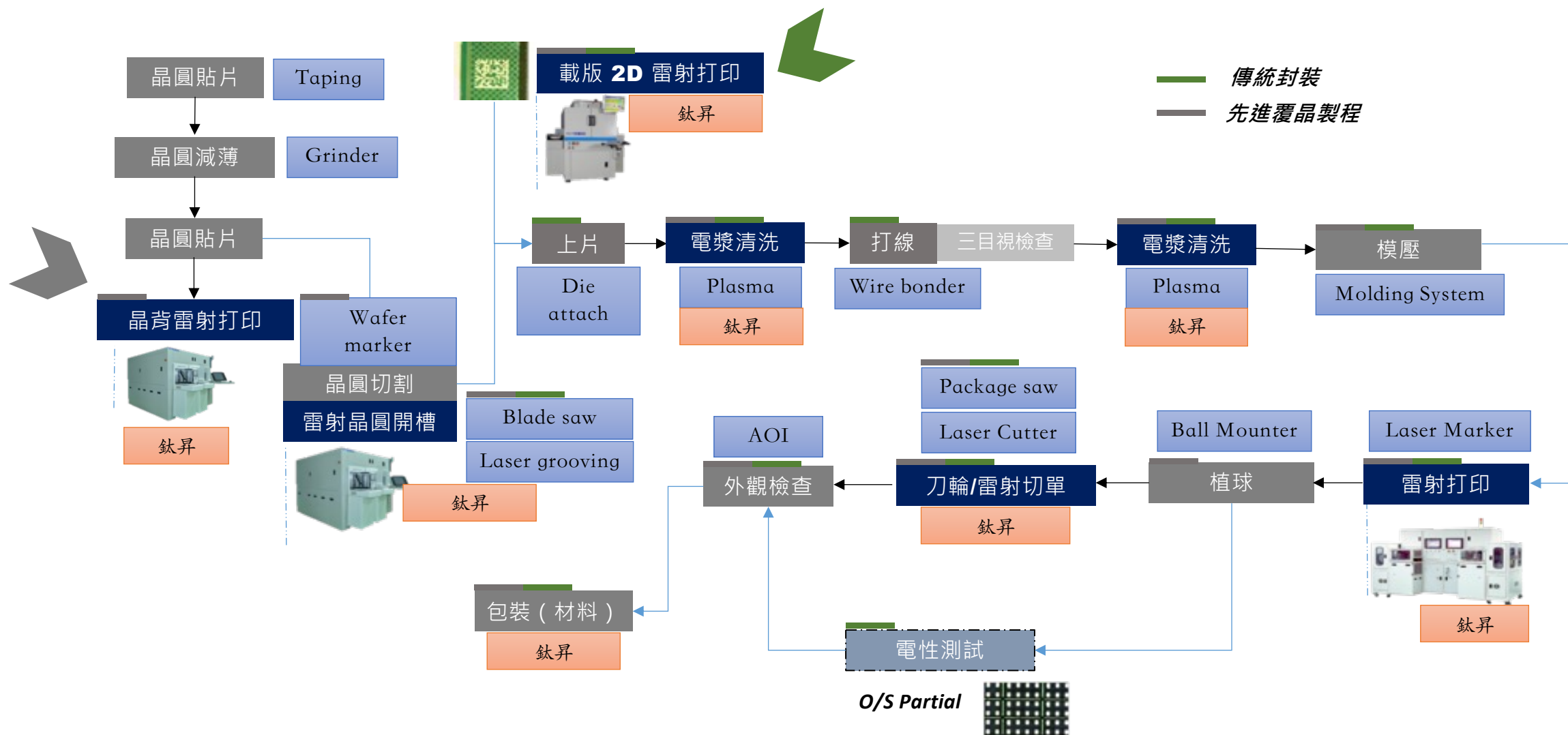


其他設備

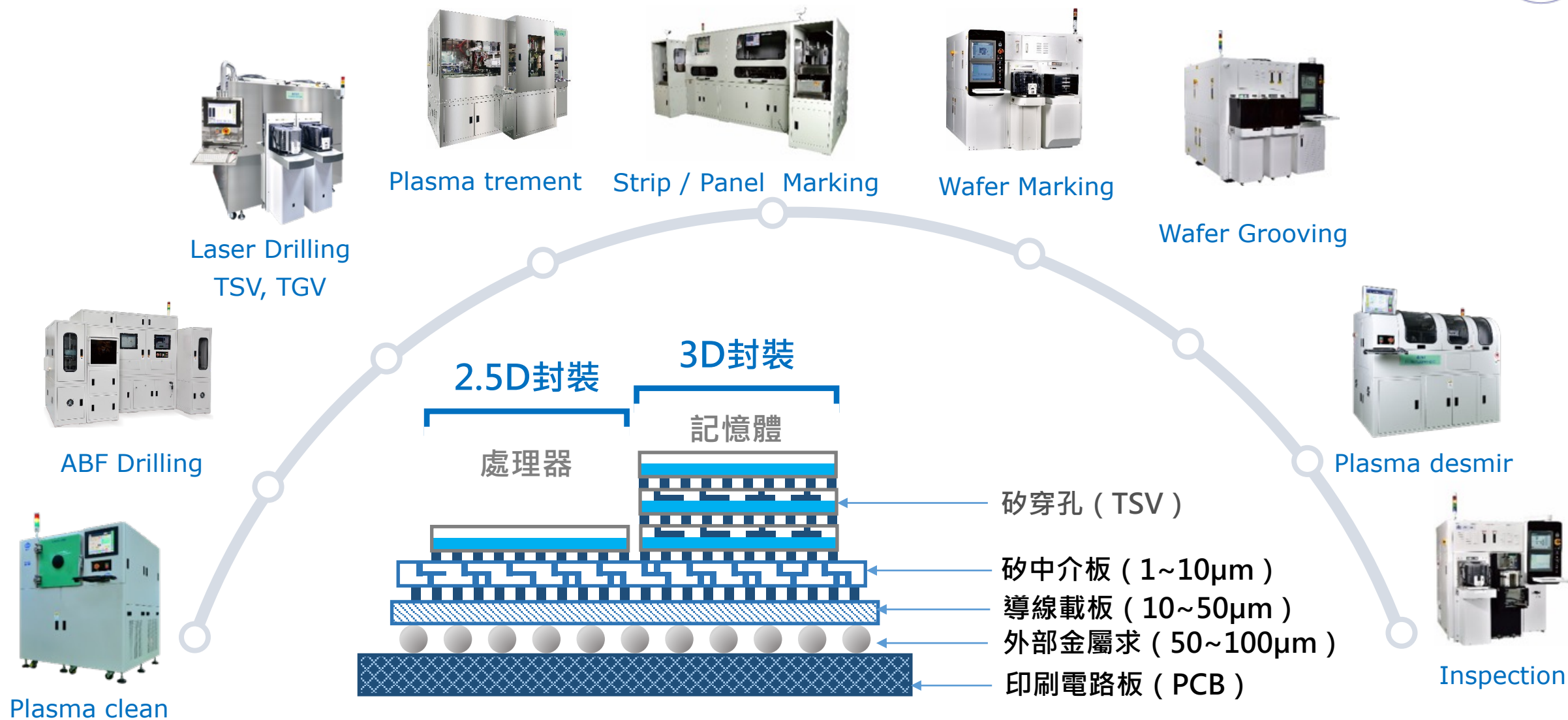
高精度SIP雷射打印、乾冰清洗、軟板雷射切割。

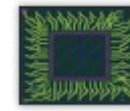
Traditional Process

IC, Discrete, LED



Advanced Process





Laser tech



Lead Frame
Substrate
2DID Marking



EOL Package
Lead Frame
Substrate
Marking



EOL Package
Boat type
Substrate
Marking



Test Line
Tray type
Marking



CO2 Snow
Dry Ice Clean



COF/TIF
Laser Marking



SIP Package
Laser Marking
trench, cutting



Laser
Cutting

Plasma tech



RF Batch
Plasma Clean



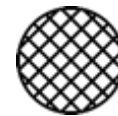
RF In-line
Plasma Clean



Microwave Batch
Plasma Clean



Microwave In-line
Plasma Clean



Laser tech



Wafer 2D
ID Marking



Wafer
Dicing
Cutting



Wafer
Topside
Marking



Wafer
Drilling



Wafer
Backside
Marking



Glass
Drilling



Wafer Grooving
Wafer Backside
Scribing

Plasma tech



Wafer RF
Plasma Clean



Wafer
Microwave
Plasma
Clean/Descum/Etch



Wafer
Microwave
Plasma Dicing

Others



Si/SiC/GaN/Wa
fer Raman & PL
Tools



Si/SiC/GaN/Wa
fer Raman & PL
Tools



Wafer AI+AOI
Tools



Laser tech



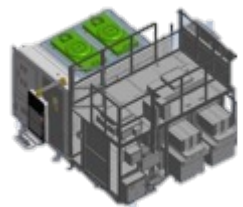
Panel 2D ID
Laser marker



Panel
Laser Marking & Cutting + sorter



Defect mark & Sorter



Glass Panel
Panel Laser Modification
Panel Laser Applications x 6 Apps

Plasma tech

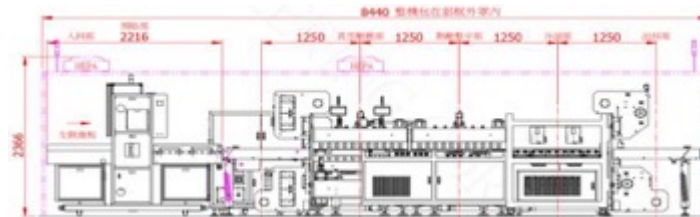


600/700mm
Microwave Plasma
Clean/Descum/Etch

Others



Panel AI+AOI Tools



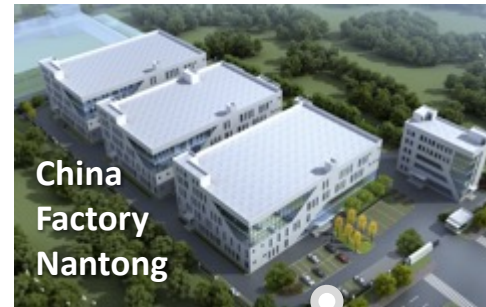
Panel
Lamination



Future Outlook 公司展望

Technical Milestones 2022 ~

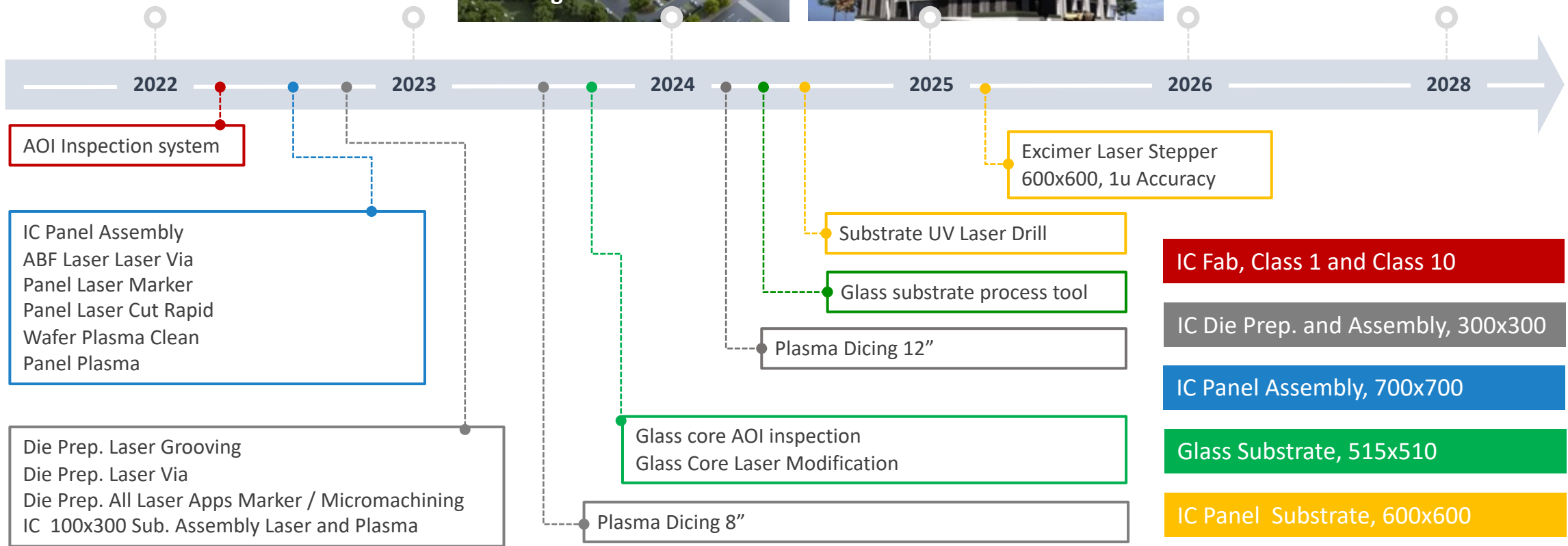
Semiconductor Innovation Provider for Laser Tools
Dry Micro-Machining Innovation



China
Factory
Nantong



Global New HQ in Taiwan
Class 100





特色

- 獨家可供應專線多種雷射與電漿設備。

產品競爭優勢

- 2023H1 已進入量產 (700mm x700mm) 。

ABF Wafer Laser Via

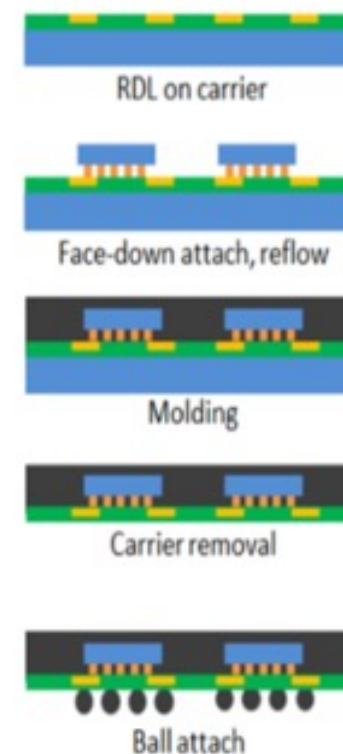
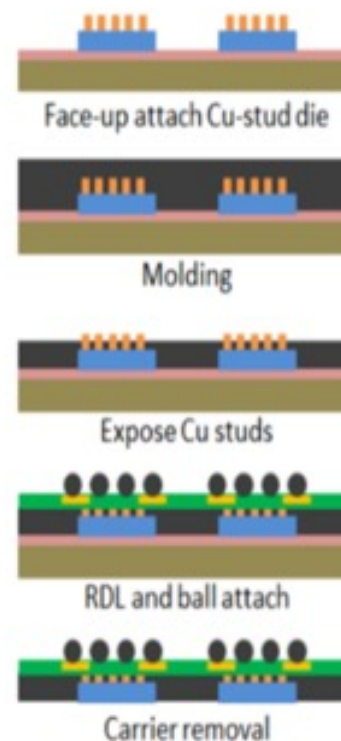
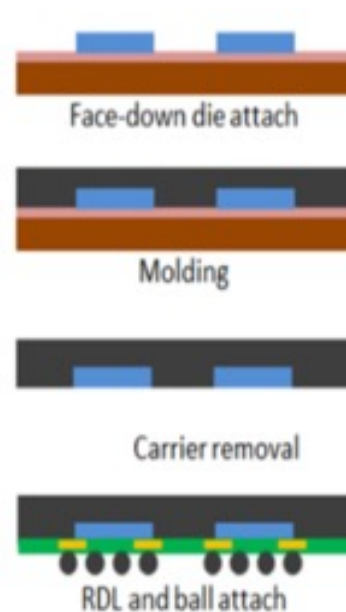
Panel Laser Marker

Panel Laser Cut

Wafer Plasma Clean

Wafer Ring Plasma

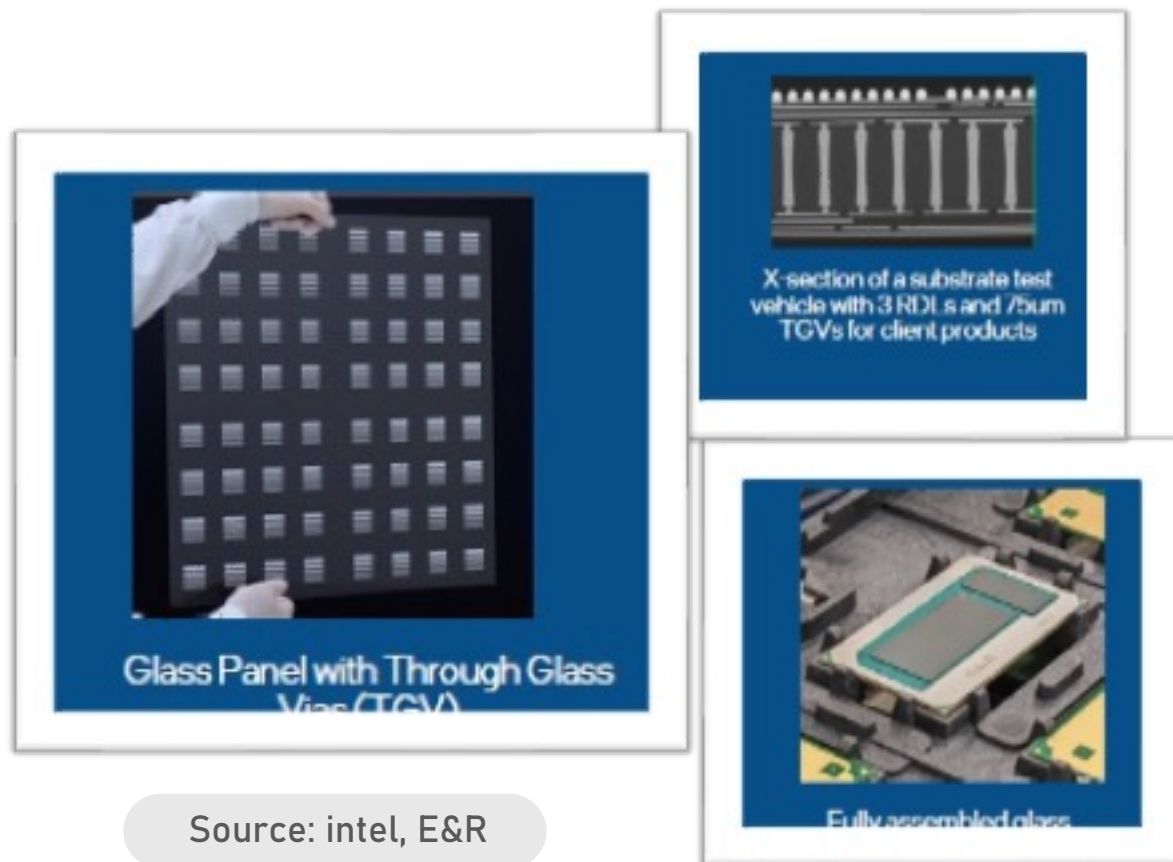
Panel Plasma clean





▶ 特色

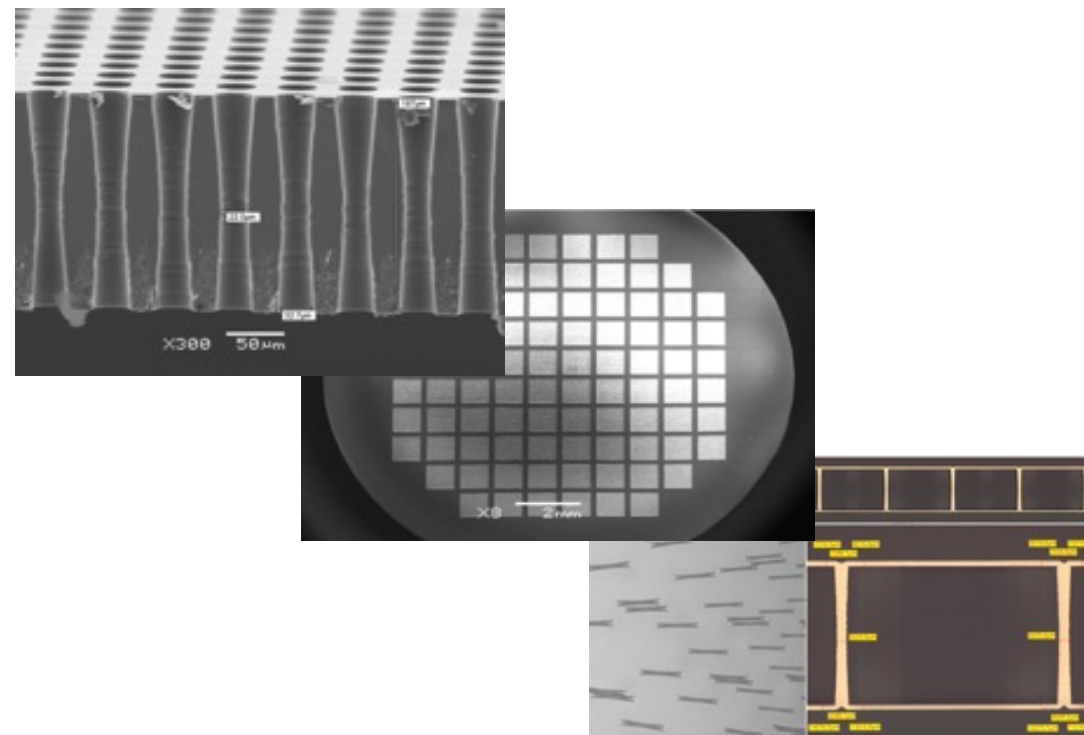
- 使用高階雷射搭配專利製程。



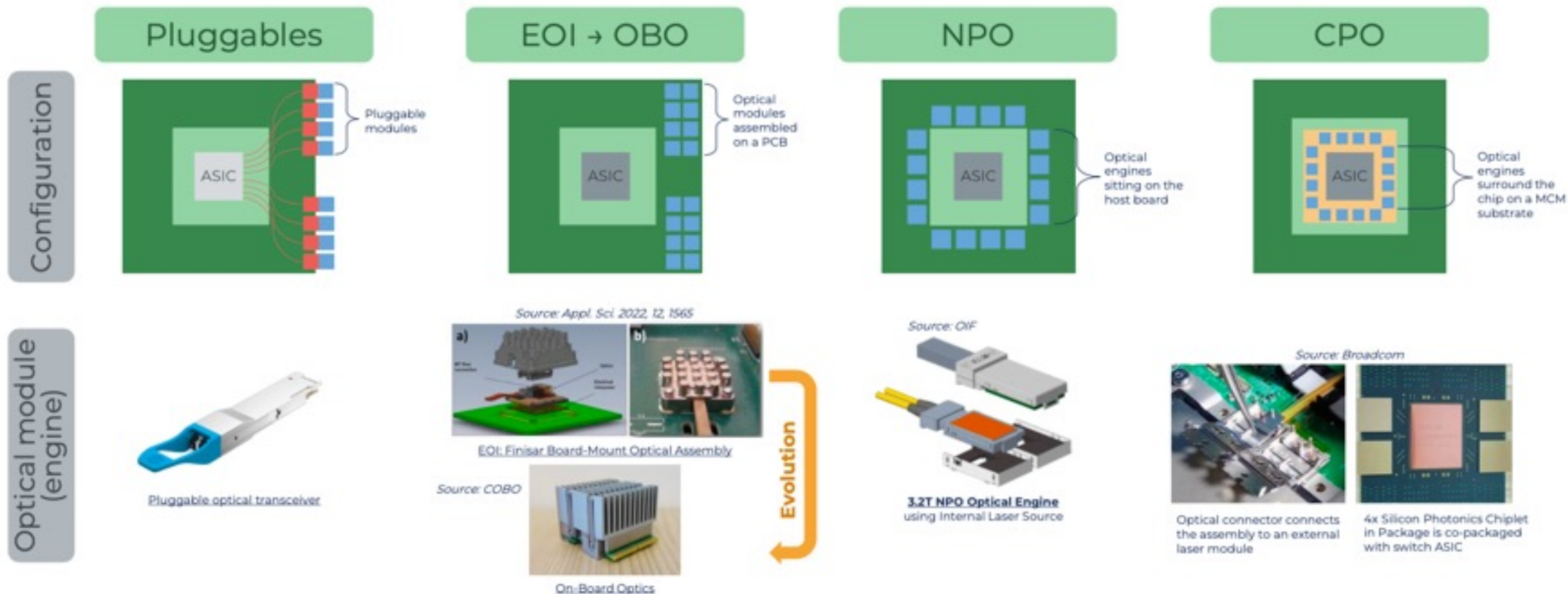
Source: intel, E&R

▶ 產品競爭優勢

- 獨特設計建立高競爭產出屏障。
- 獨家通過量產線驗證合格。
- 獨家提供7種以上設備。



Long-Term CPO Application – 矽光子技術開發



CPO示意圖 Source: Yole



Q&A

問答時間

THANK YOU

Contact us

Visit us to have more details via



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